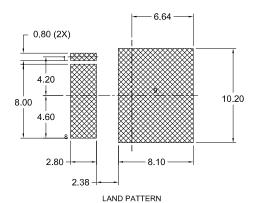


# В (2x) a ccc D2 (2x) TERMINAL 1 CORNER Α INDEX AREA <u>5</u> (DATUM A) b (8x) bbbM C A B D4 (2x) E2 (2x) ddd(M) C L2 (8x) ·L1 🙆 SECTION "A-A" TOP VIEW DETAIL "B" η(4X) <del>Θ</del> // aaa C SIDE VIEW D1 DETAIL "B" SCALE: 2X D5 (2x) D6 D3 (2x)

## H-PSOF8L 11.68x9.80x2.30, 1.20P CASE 100CU **ISSUE F**

#### **DATE 30 JUL 2024**



RECOMMENDATION \*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ONSEMI SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

#### NOTES:

SCALE: 2X

- 1. PACKAGE STANDARD REFERENCE: JEDEC MO-299, ISSUE B.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
- 3. "e" REPRESENTS THE TERMINAL PITCH.
- 4. THIS DIMENSION INCLUDES ENCAPSULATION THICKNESS "A1", AND PACKAGE BODY THICKNESS, BUT DOES NOT INCLUDE ATTACHED FEATURES, e.g., EXTERNAL OR CHIP CAPACITORS. AN INTEGRAL HEATSLUG IS NOT CONSIDERED AS ATTACHED FEATURE. 5. A VISUAL INDEX FEATURE MUST BE LOCATED WITHIN THE
- HATCHED AREA 6. DIMENSIONS b1,L1,L2 APPLY TO PLATED TERMINALS.
- 7. THE LOCATION AND SIZE OF EJECTOR MARKS ARE OPTIONAL.
  8. THE LOCATION AND NUMBER OF FUSED LEADS ARE OPTIONAL.

ЫМ	MILLIMETERS			
21111	MIN.	NOM.	MAX.	
Α	2.20	2.30	2.40	
A1	1.70	1.80	1.90	
b	0.70	0.80	0.90	
b1	9.70	9.80	9.90	
b2	0.35	0.45	0.55	
С	0.40	0.50	0.60	
D	10.28	10.38	10.48	
D/2	5.09	5.19	5.29	
D1	10.98	11.08	11.18	
D2	3.20	3.30	3.40	
D3	2.60	2.70	2.80	
D4	4.45	4.55	4.65	
D5	3.20	3.30	3.40	
D6	0.55	0.65	0.75	
E	9.80	9.90	10.00	
E1	7.30	7.40	7.50	
E2	0.30	0.40	0.50	
E3	7.40	7.50	7.60	
E4	8.20	8.30	8.40	

DIM	MILLIMETERS			
Divi	MIN.	NOM.	MAX.	
E5	9.36	9.46	9.56	
E6	1.10	1.20	1.30	
E7	0.15	0.18	0.21	
е	1.20 BSC			
e/2	0.60 BSC			
Н	11.58	11.68	11.78	
H/2	5.74	5.84	5.94	
H1	7.15 BSC			
L	1.90	2.00	2.10	
L1	0.60	0.70	0.80	
L2	0.50	0.60	0.70	
L3	0.70	0.80	0.90	
θ	10° REF			
Θ1	10° REF			
aaa	0.20			
bbb	0.25			
CCC	0.20			
ddd	0.20			
eee	0.10			

### **BOTTOM VIEW GENERIC MARKING DIAGRAM\***

(2x)

F6 (3x)

E1 E3 E4 F5

HEAT SLUG TERMINAL

Α = Assembly Location

D/2

= Year

L3

(DATUM A)

√ b2 (8x)

<u>/8</u>\

L (8x)

(DATUM B)

WW = Work Week

= Assembly Lot Code XXXX = Specific Device Code

AYWWZZ XXXXXXX XXXXXXX

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	H-PSOF8L 11.68x9.80x2.30, 1.20P		PAGE 1 OF 1	

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